

Title (en)

ELECTROPLATED PRODUCTS AND ELECTROPLATING BATH FOR PROVIDING SUCH PRODUCTS

Title (de)

ELEKTROPLATTIERTE PRODUKTE UND ELEKTROPLATTIERUNGSBAD ZUR BEREITSTELLUNG SOLCHER PRODUKTE

Title (fr)

PRODUITS ÉLECTROPLAQUÉS ET BAIN D'ÉLECTROPLACAGE POUR OBTENIR LESDITS PRODUITS

Publication

EP 3765658 A1 20210120 (EN)

Application

EP 19709513 A 20190313

Priority

- EP 18161575 A 20180313
- EP 2019056328 W 20190313

Abstract (en)

[origin: EP3540097A1] The present invention relates to electroplated products having a combination of layers used to provide a diffusion barrier layer under a precious metal top layer on a substrate comprising a copper based material and/or a copper based underlayer, such that the layer or combination of layers prevents or retards the migration of copper into the precious metal layer or the opposite. The diffusion barrier layer comprises indium or an indium alloy. Moreover, the present invention refers a method for preparing such an electroplated product.

IPC 8 full level

C25D 7/00 (2006.01); **C25D 3/54** (2006.01); **C25D 3/56** (2006.01); **C25D 3/62** (2006.01); **C25D 5/10** (2006.01)

CPC (source: EP US)

C25D 3/54 (2013.01 - EP); **C25D 3/56** (2013.01 - EP); **C25D 3/62** (2013.01 - EP); **C25D 5/10** (2013.01 - EP US); **C25D 5/611** (2020.08 - EP US); **C25D 5/627** (2020.08 - EP US); **C25D 7/005** (2013.01 - EP)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 3540097 A1 20190918; EP 3765658 A1 20210120; EP 3765658 B1 20230614; ES 2970912 T3 20240531; WO 2019175270 A1 20190919

DOCDB simple family (application)

EP 18161575 A 20180313; EP 19709513 A 20190313; EP 2019056328 W 20190313; ES 19709513 T 20190313